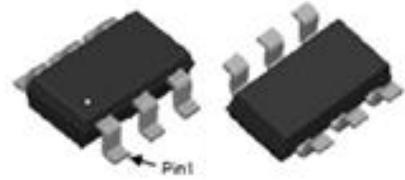
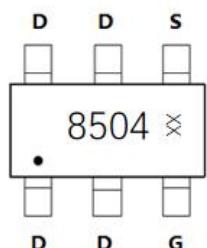




## Description

<b>JMT P-channel Enhancement Mode Power MOSFET</b>	
<b>Features</b> <ul style="list-style-type: none"><li><math>V_{DS} = -40V</math>, <math>I_D = -5A</math></li><li><math>R_{DS(ON)} &lt; 85m\Omega</math> @ <math>V_{GS} = -10V</math></li><li><math>R_{DS(ON)} &lt; 115m\Omega</math> @ <math>V_{GS} = -4.5V</math></li><li>Advanced Trench Technology</li><li>Excellent <math>R_{DS(ON)}</math> and Low Gate Charge</li><li>Lead free product is acquired</li></ul>	<b>Application</b> <ul style="list-style-type: none"><li>PWM Applications</li><li>Load Switch</li><li>Power Management</li></ul> 
 SOT-23-6L top view	 Marking and pin Assignment

## Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
8504	JMTM850P04A	TAPING	SOT-23-6L	7inch	3000	120000

## Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise specified)

Symbol	Parameter	Max.	Units
$V_{DSS}$	Drain-Source Voltage	-40	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current $T_A = 25^\circ C$	-5	A
		$-3.3$	A
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>	-20	A
$P_D$	Power Dissipation $T_A = 25^\circ C$	3.4	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	37	$^\circ C/W$
$T_J$ , $T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^\circ C$

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

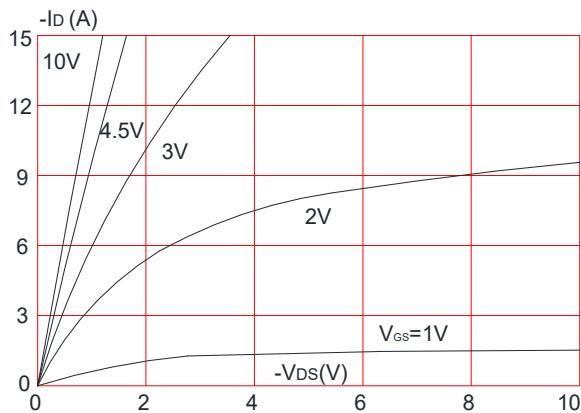
Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristics</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D = -250\mu\text{A}$	-40	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS} = -40\text{V}$ , $V_{GS}=0\text{V}$	-	-	-1	$\mu\text{A}$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0\text{V}$ , $V_{GS} = \pm 20\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D = -250\mu\text{A}$	-1.0	-1.6	-2.5	V
$R_{DS(\text{on})}$ note3	Static Drain-Source on-Resistance	$V_{GS} = -10\text{V}$ , $I_D = -3\text{A}$	-	66	85	$\text{m}\Omega$
		$V_{GS} = -4.5\text{V}$ , $I_D = -2\text{A}$	-	82	115	
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS} = -20\text{V}$ , $V_{GS}=0\text{V}$ , $f=1.0\text{MHz}$	-	573	-	pF
$C_{oss}$	Output Capacitance		-	53	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	42	-	pF
$Q_g$	Total Gate Charge	$V_{DS} = -20\text{V}$ , $I_D = -3\text{A}$ , $V_{GS} = -10\text{V}$	-	7.1	-	nC
$Q_{gs}$	Gate-Source Charge		-	1.5	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	1.8	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = -20\text{V}$ , $I_D = -5\text{A}$ , $V_{GS} = -10\text{V}$ , $R_{\text{GEN}} = 2.5\Omega$	-	6.5	-	ns
$t_r$	Turn-on Rise Time		-	14	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	34	-	ns
$t_f$	Turn-off Fall Time		-	18	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_s$	Maximum Continuous Drain to Source Diode Forward Current	-	-	-5	-	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	-20	-	A
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_s = -5\text{A}$	-	-0.8	-1.2	V
$trr$	Reverse Recovery Time	$V_{GS}=0\text{V}$ , $I_s = -5\text{A}$ , $di/dt = 100\text{A}/\mu\text{s}$	-	23	-	ns
$Qrr$	Reverse Recovery Charge		-	25.2	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

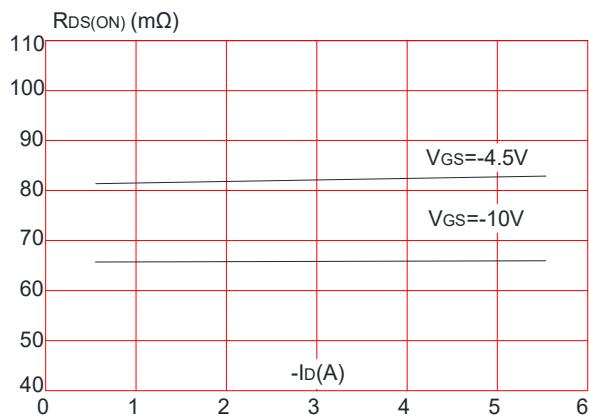
2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 2\%$

## Typical Performance Characteristics

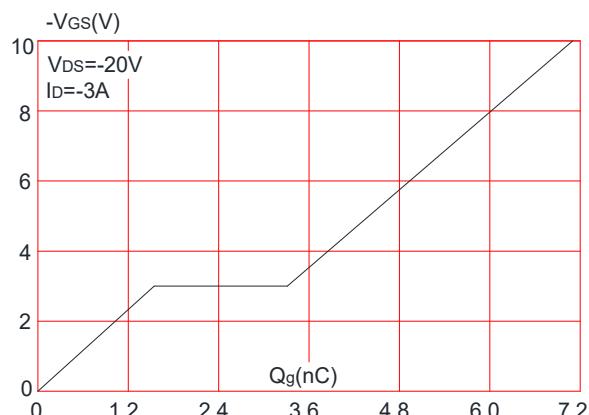
**Figure 1:** Output Characteristics



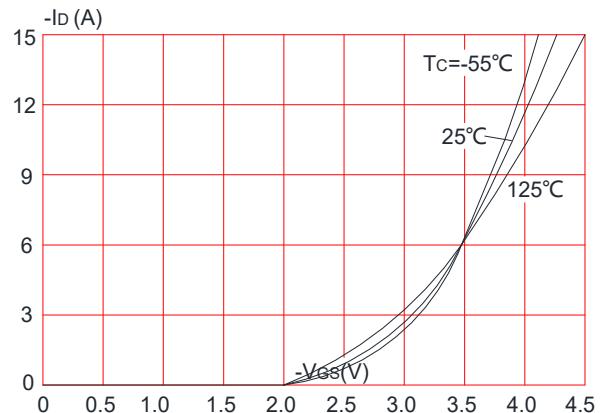
**Figure 3:** On-resistance vs. Drain Current



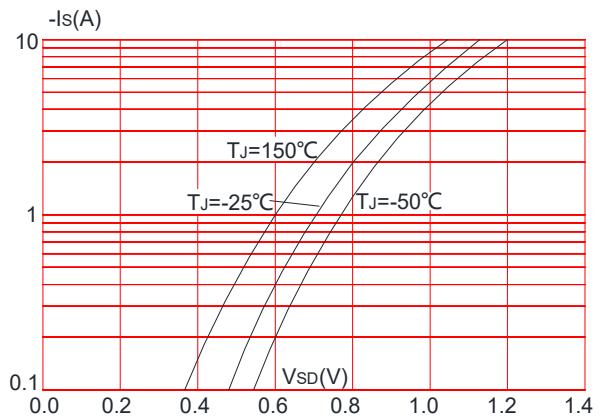
**Figure 5: Gate Charge Characteristics**



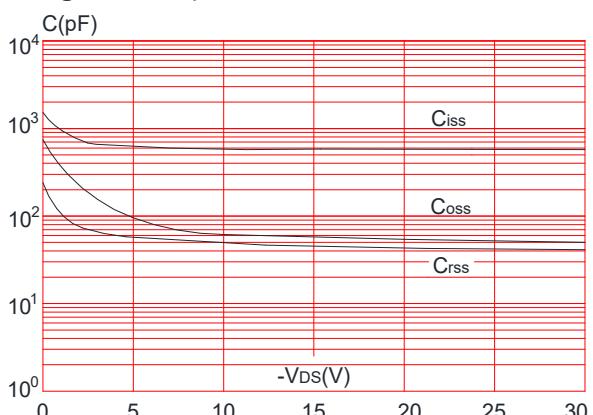
**Figure 2:** Typical Transfer Characteristics



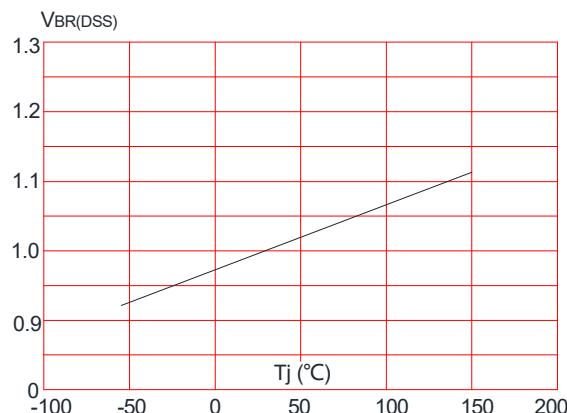
**Figure 4:** Body Diode Characteristics



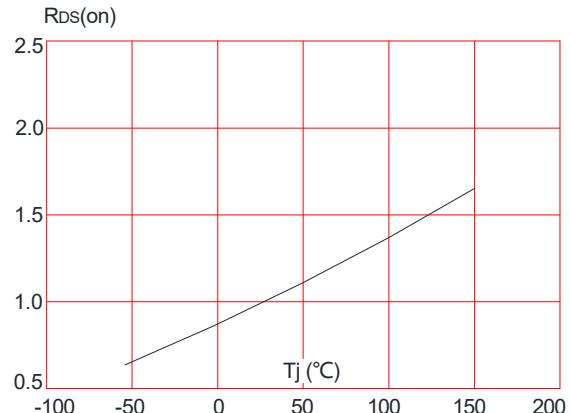
**Figure 6: Capacitance Characteristics**



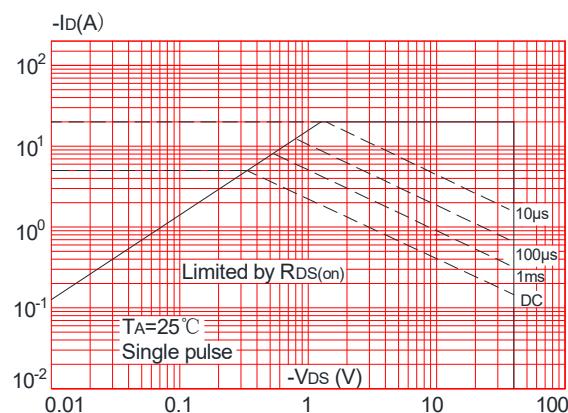
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



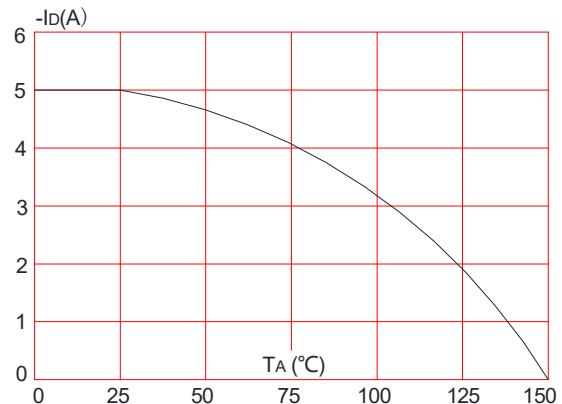
**Figure 8:** Normalized on Resistance vs. Junction Temperature



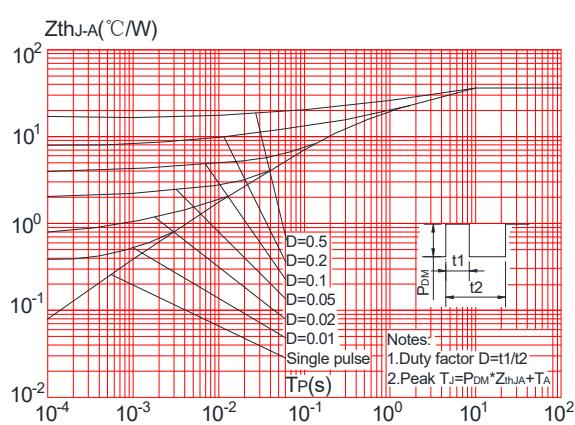
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature

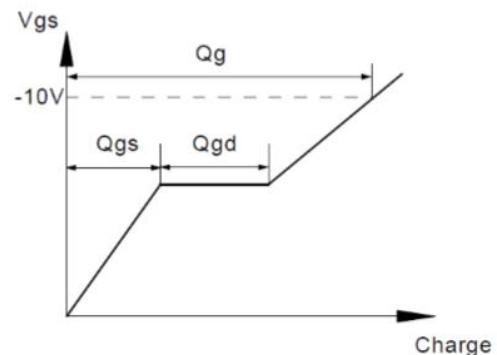
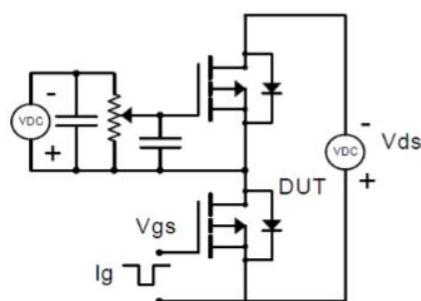


**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

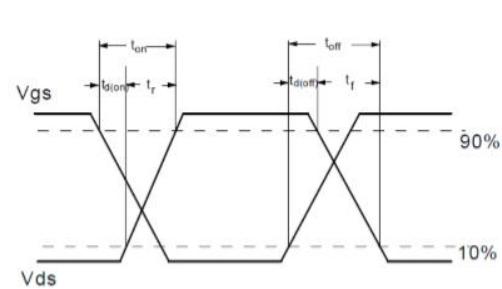
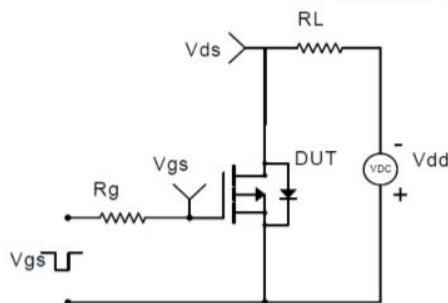


## Test Circuit

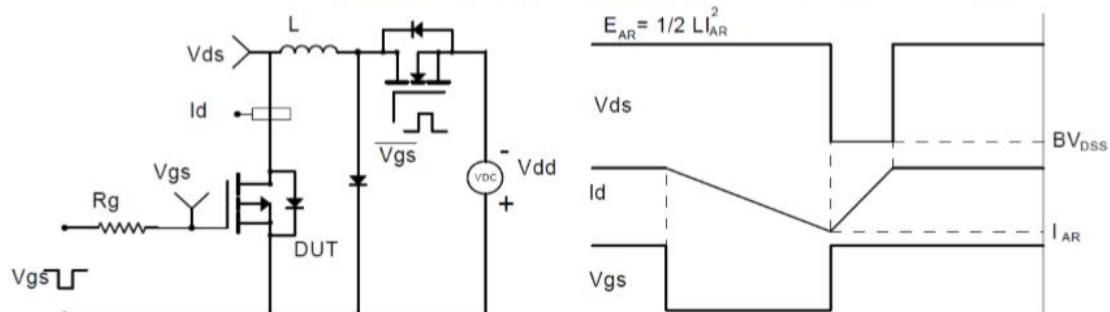
Gate Charge Test Circuit & Waveform



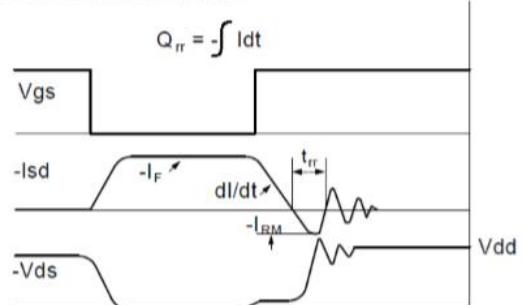
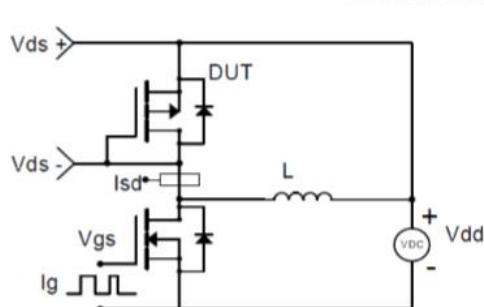
Resistive Switching Test Circuit & Waveforms



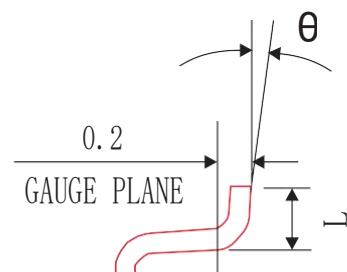
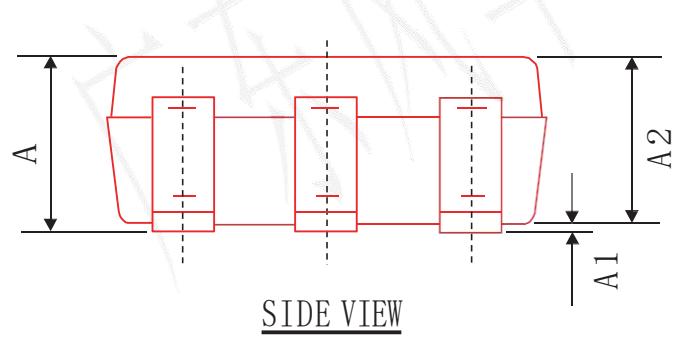
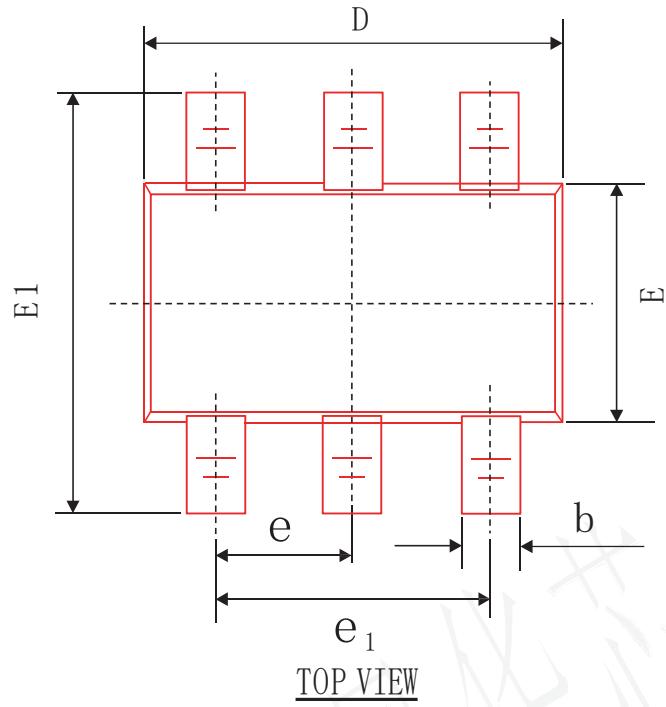
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



## Package Mechanical Data- SOT-23-6L



SYMBOL	MIN	NOM	MAX
A	—	—	1.20
A1	0.00	0.05	0.10
A2	1.00	1.10	1.20
b	0.30	0.40	0.50
c	0.119	0.127	0.135
e <sub>1</sub>	1.80	1.90	2.00
D	2.80	2.90	3.00
E	1.50	1.60	1.70
E1	2.60	2.80	3.00
L	0.30	0.45	0.60
θ	0°	4°	8°
e	0.95BSC		



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